

# Reverse Annealing Comparisons of PnP and Npn III-V HBTs under Ion Irradiation – Probing the Effects of Thermal and Current Injection Annealing



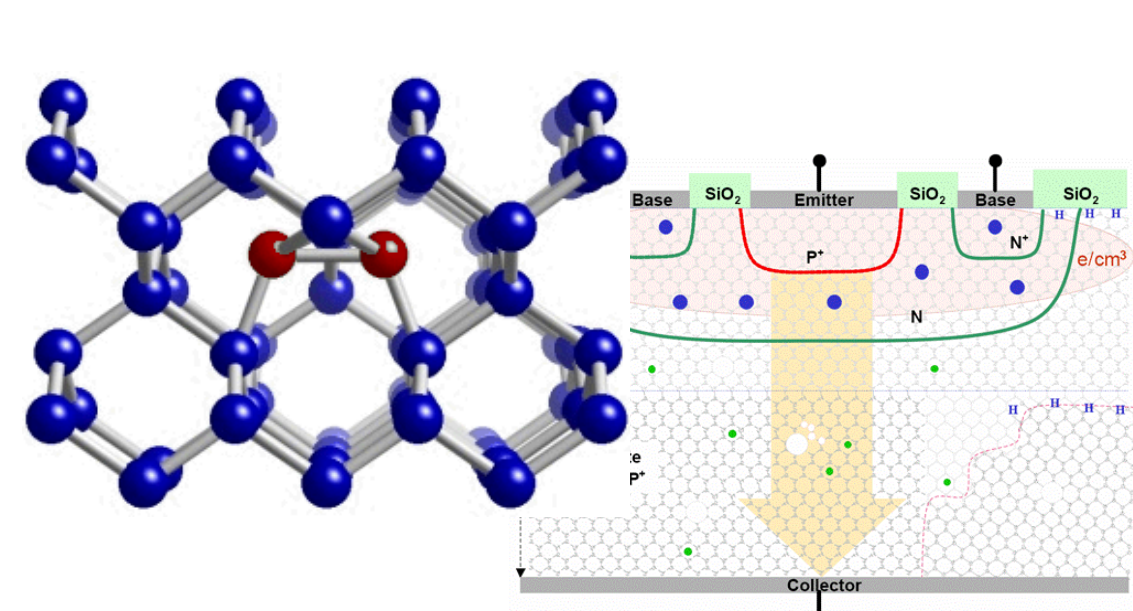
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## Abstract

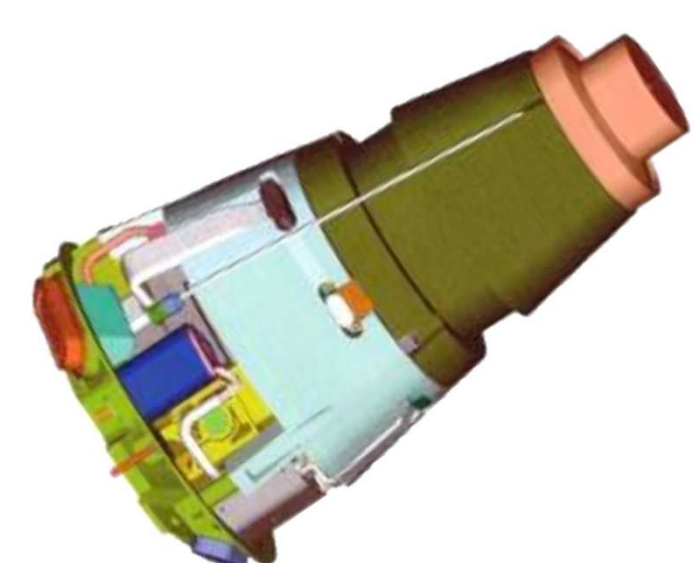
We present a comparison of early-time reverse annealing in PnP and Npn HBTs. We find that while the PnPs demonstrate reverse annealing, for equivalent conditions (ion species, temperature, etc...) Npns show a much stronger current injection annealing due to difference in current density under the same operating conditions.

## Defect Study Motivation

### Radiation Effects



Fundamental Radiation Induced Defects



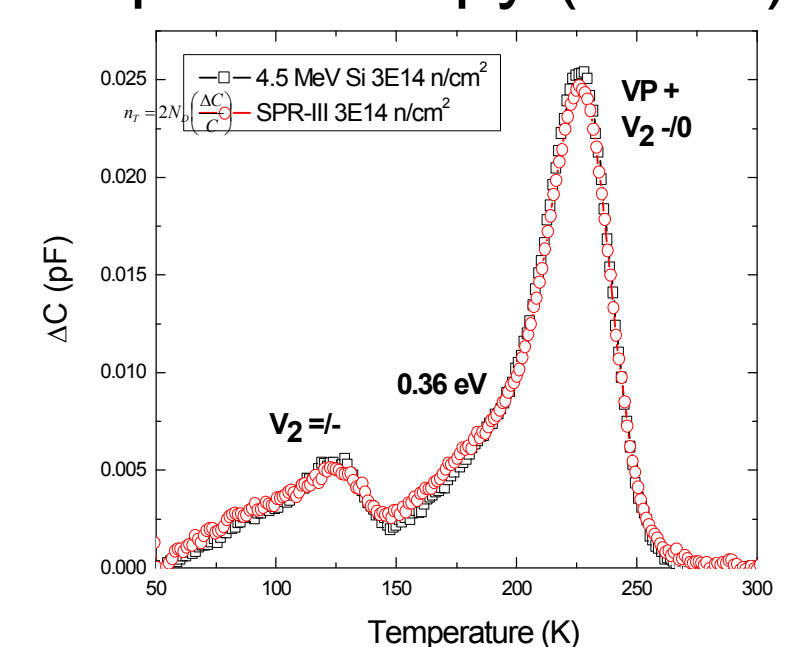
Degradation of Device/Circuit Performance

Of particular interest is early-time (<1s) gain degradation

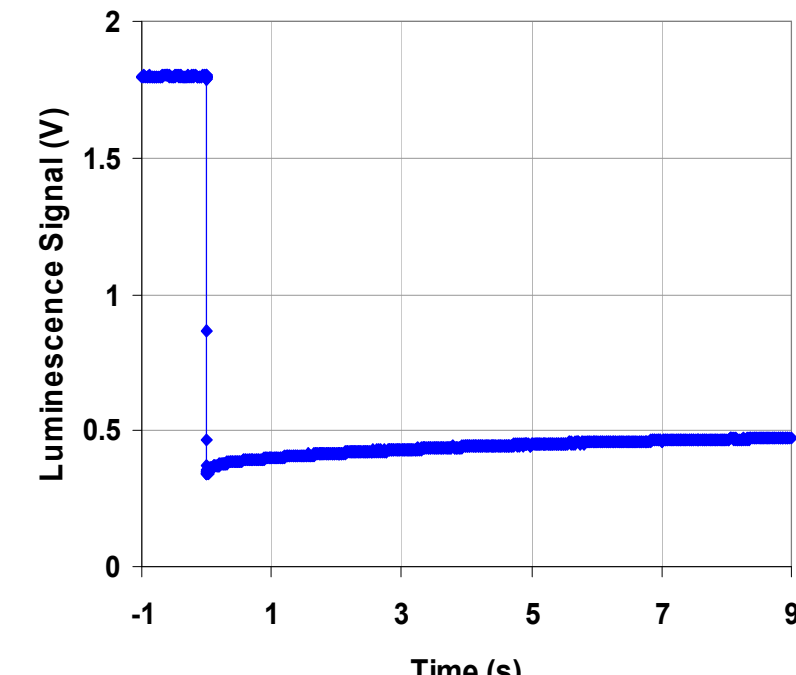
### Experimental Techniques

We use a series of *in-situ* techniques to explore the defect creation and annealing

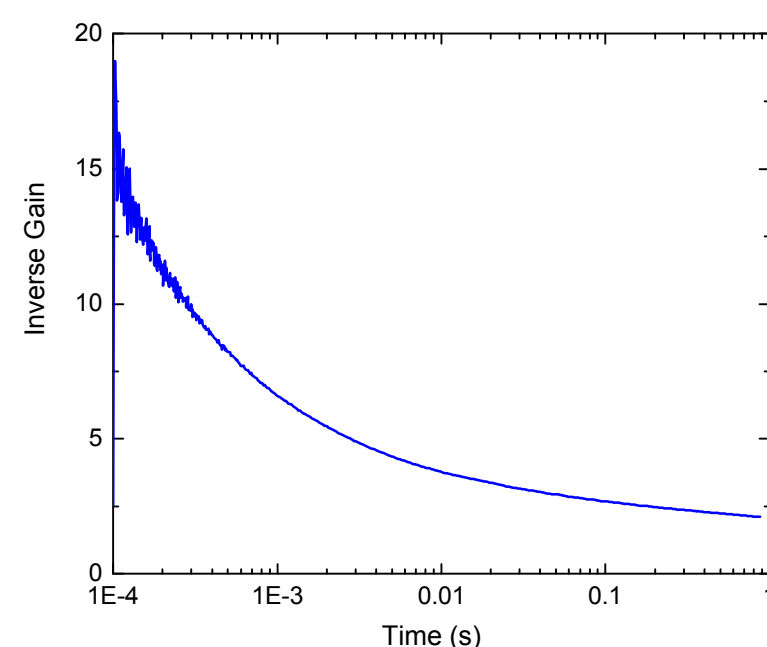
#### Deep-level Transient Spectroscopy (DLTS)



#### Photoluminescence



#### Active Gain

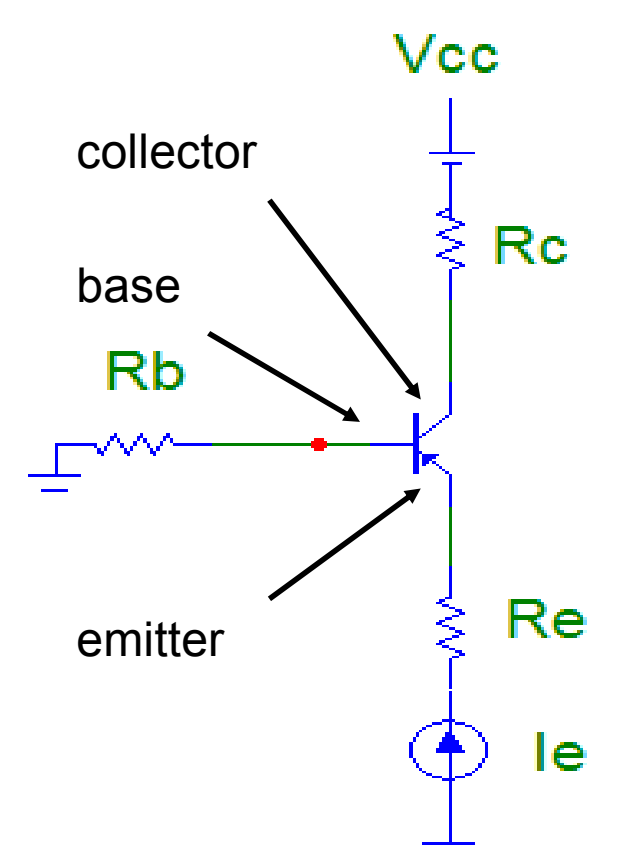
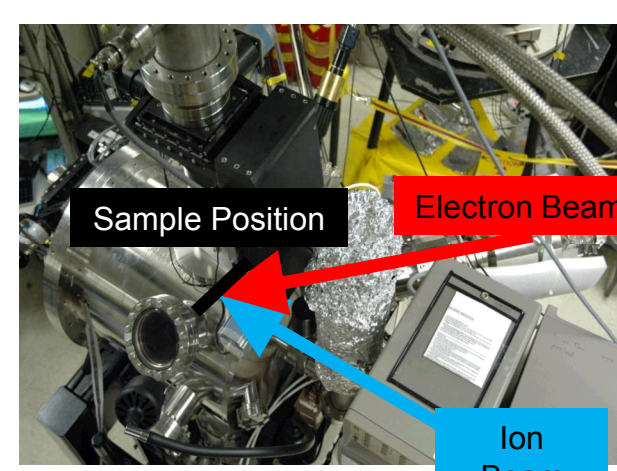


## Measurement Setup and Gain Response

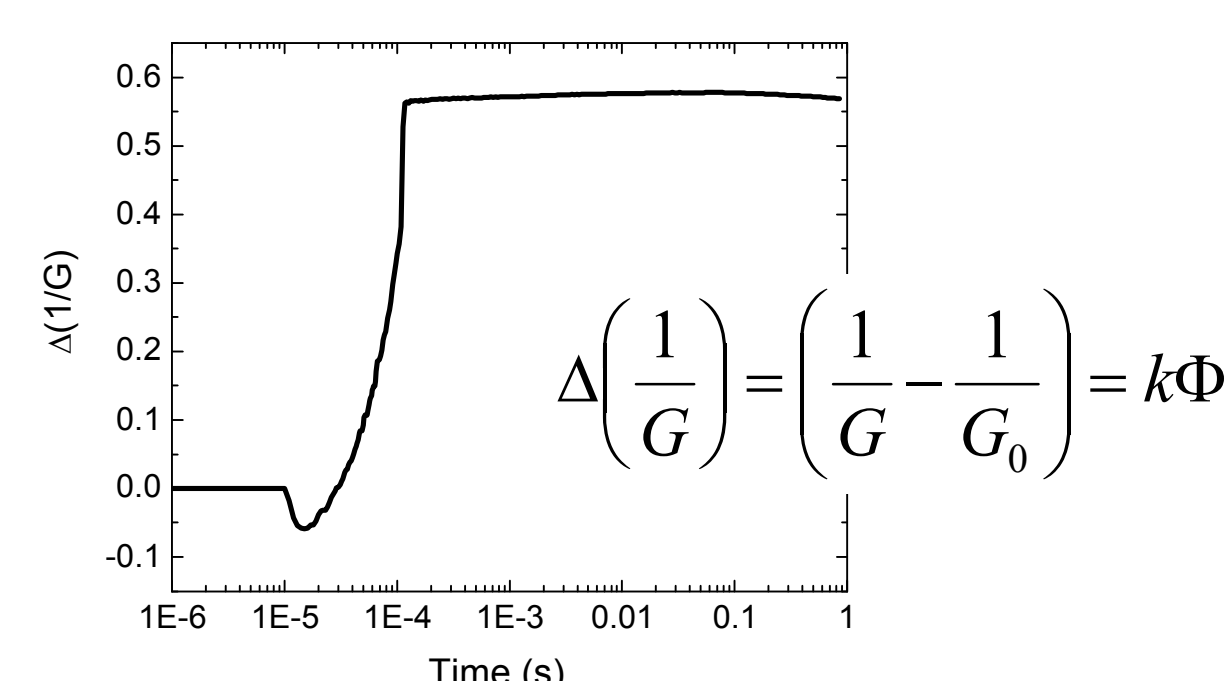
#### 6 MV Tandem Accelerator



#### Combined Heavy Ion and Electron Irradiation End-station

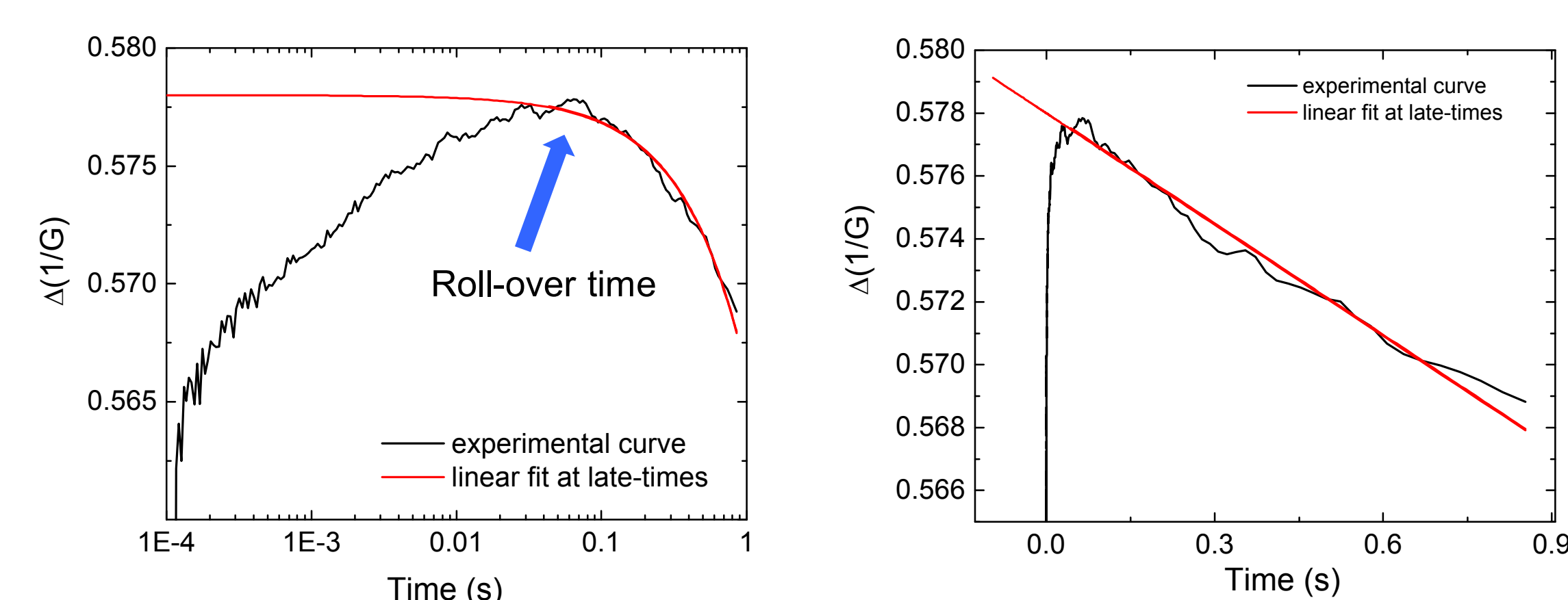


#### End-of-Range 9 MeV Si Irradiation



All devices operated at fixed emitter current of 0.22 mA, with a  $V_{BC}$  of 4 V

## The Effect: Post-Irradiation Gain Degradation



$\Delta(1/G)$  increases during the pulse due to damage, BUT does not show annealing immediately after the irradiation rather it shows damage continuing to build in for ~0.1 s after the pulse (reverse annealing).

## Exploration of Post-Irradiation Gain Degradation

#### Late-time ions:

No late-time ions observed

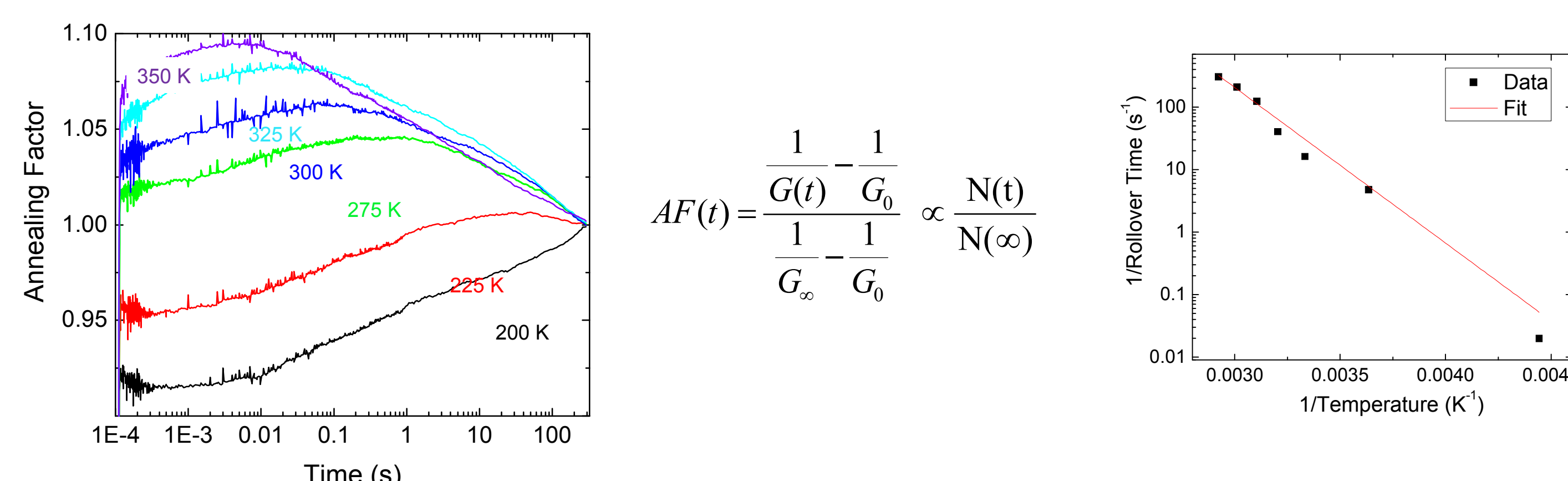
#### Heating Effects:

Negligible Ion Heating Effects

#### Temperature Dependence:

Strong temperature effect observed in continuous-on experiments

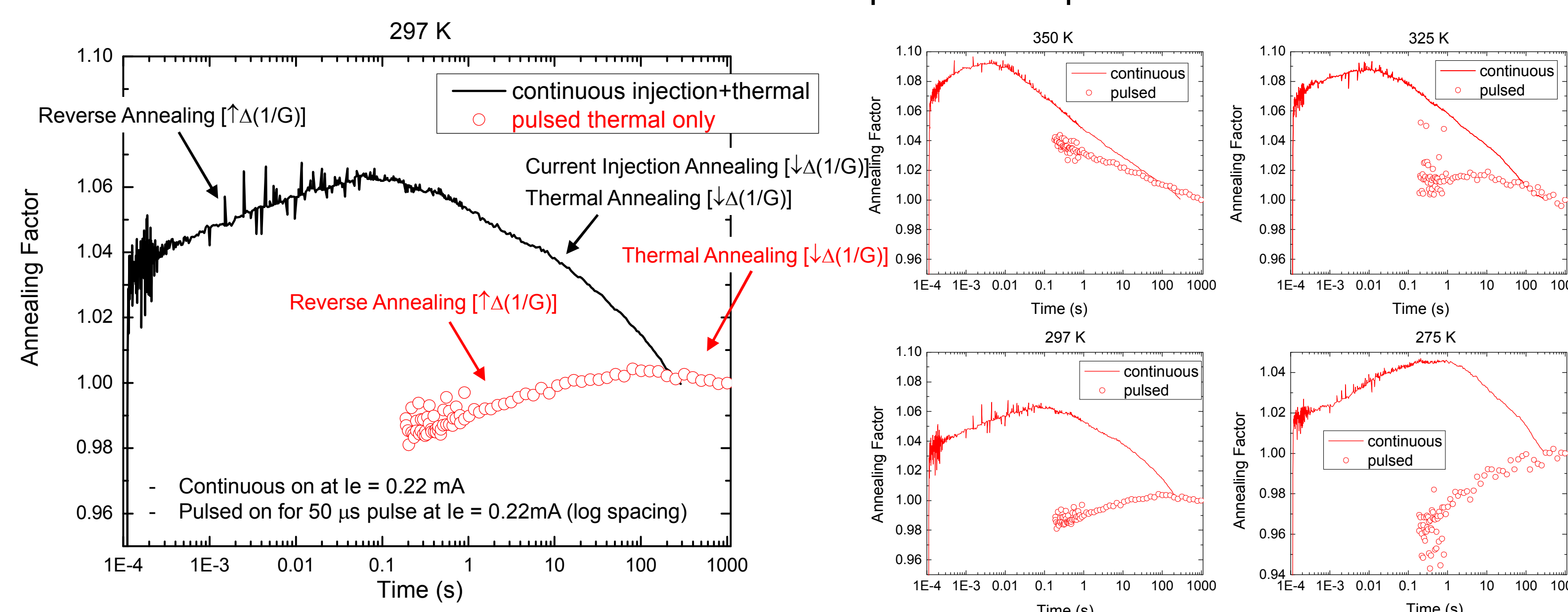
## Temperature Dependence of the Reverse Annealing



Observe a dramatic temperature dependence, plotting 1/roll-over time we find an Arrhenius behavior with a 0.5 eV activation energy

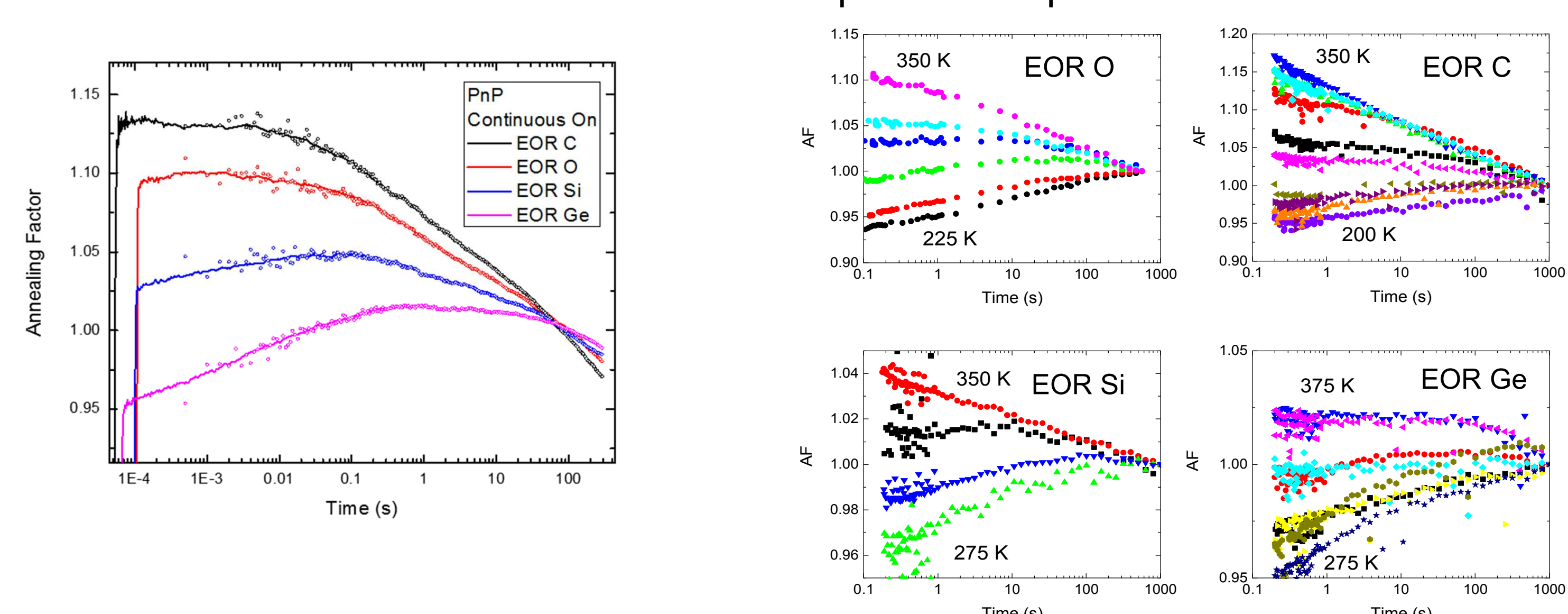
## Pulsed Current Setup Isolating Thermal vs. Injection Annealing

### Temperature Dependence of Pulsed Current Setup



## Ion Species Dependence of the Reverse Annealing

### Temperature Dependence of Pulsed Current Setup



### Potential Interpretation - Local Cluster Environment Effects

From 1960's n-type GaAs work we know neutron and electron damage have different annealing stages

#### Electron

Stage I 493 K (complete recovery)

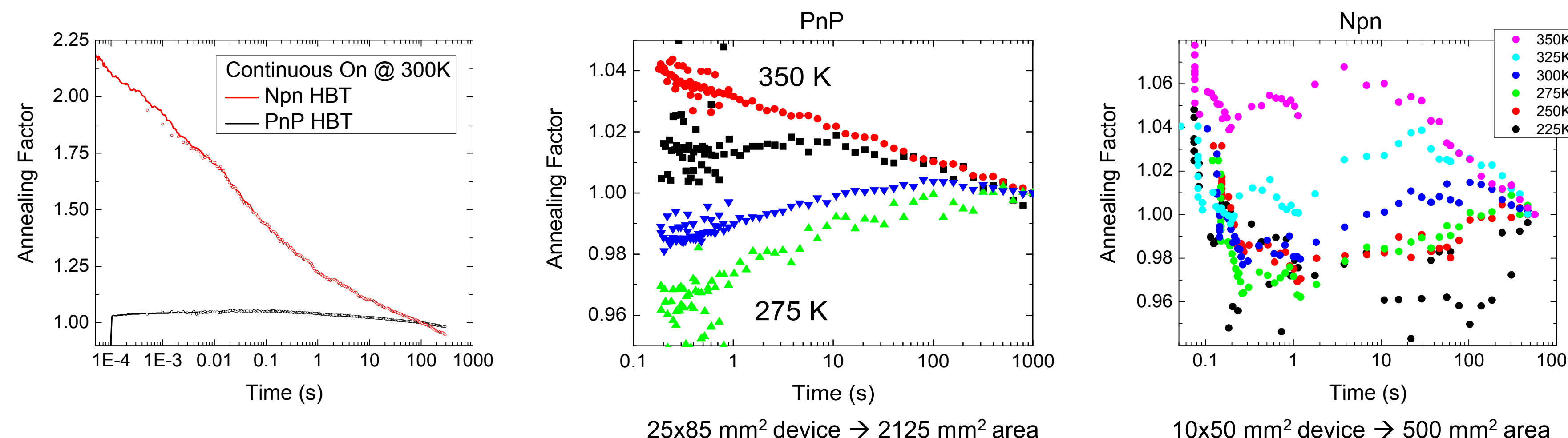
#### Fast Neutron

Stage I 493 K  
Stage II 723 K  
Stage III 873-973 K

This suggests that it is the local clustering environment that is responsible from the change in the annealing behavior when changing ion species:

- C → smallest clustering, fastest annealing even at low temperatures (200 K)
- Si → intermediate clustering, we bracket the annealing behavior
- Ge → largest clustering, slowest annealing even at high temperatures (375 K)

## PnP and Npn Reverse Annealing Compared



## Conclusion

With ion irradiations we can explore transient annealing at very short times after the irradiation and have found a reverse annealing component in PnP and Npn HBTs. One potential explanation is that we are observing a thermally activated defect evolution that results in a defect complex with a larger carrier recombination cross-section that further lowers the gain after the initial Frenkel pair production has stopped. We have explored the temperature and ion species dependence of the reverse annealing and found a clear correlation between the size of the damage cluster and the extent of the reverse annealing, with larger damage clusters producing a larger reverse annealing component.